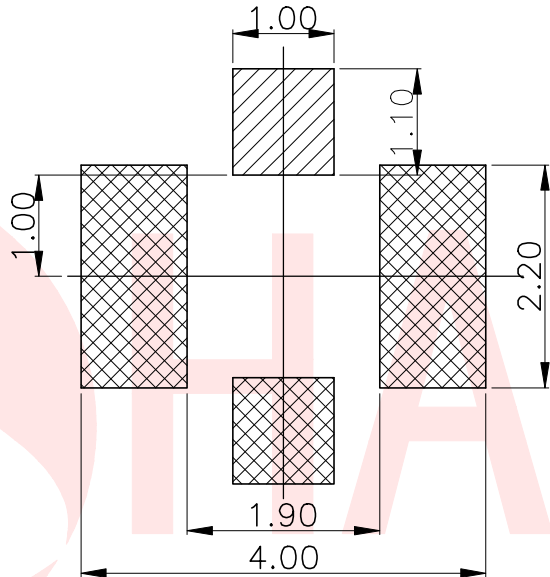
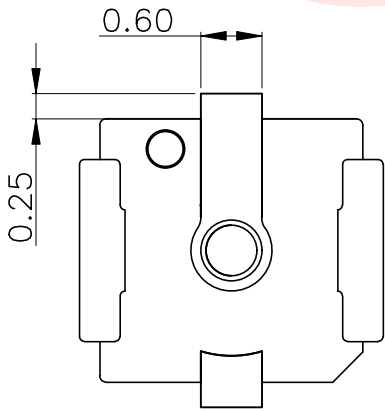
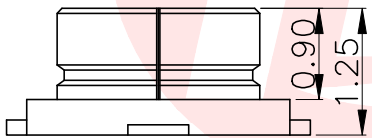
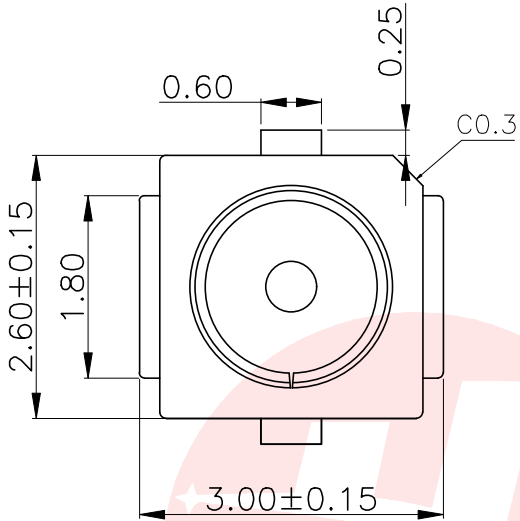


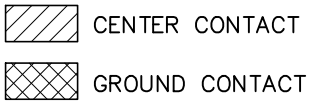


REV.	ECN NO OR DESCRIPTION	REVISED	DATE



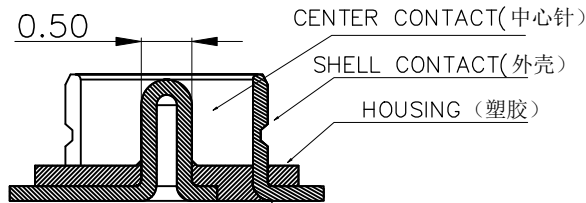
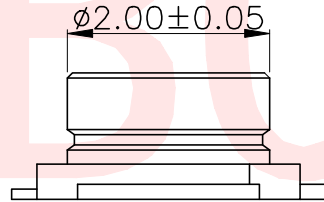
RECOMMENDED PCB LAYOUT

(TOLERANCE: ±0.05)



NOTES(备注) :

- 1.0. RATING(额定值) :
- 1.1. VOITAGE(电压) : 60 VAC (R.M.S.)
 - 1.2. NOMINAL CHARACTERISTIC IMPEDANCE(特性阻抗): 50 Ohm
 - 1.3. APPLICABLE FREQUENCY(适用频率): DC ~ 6GHz
 - 1.4. VSWR(电压驻波比): 1.3 MAX. (DC~3GHz), 1.5 MAX. (3~6GHz)
 - 1.5. TEMPERATURE(适用温度) : -40°C TO +85°C
 - 1.6. APPLIED TO IR SOLDERING PROCESS(适用回流焊接方式)
- 2.0. MATERIAL SEE BILL OF MATERIAL (材料清单):
- 2.1.HOUSING(塑胶): THERMOPLASTIC LCP,UL94V-0(LCP符合UL94V-0),
 - 2.2.CENTER CONTACT(中心端子) : COPPER ALLOY C5191(铜合金C5191).
 - 2.3.SHELL CONTACT(外壳): COPPER ALLOY C5191(铜合金C5191).



UNLESS OTHERWISE SPECIFIED TOLERANCES		 东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD			
DECIMALS: ANGLES:		TITLE MICRO RF II BAORD SMT 4 PADS TYPE			
X :±0.35	X :±2°	DWN xiong	PART NO. SP-IPEX-002S		
X.X :±0.25	X.X :±1°	CHKD lee	SCALE:1:1	UNIT: mm	
X.XX :±0.15		APVD wang	SIZE: A4	SHEET:10F 1	REV: A4
CUSTOMER COPY					